

L Number	Hits	Search Text	DB	Time stamp
2	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:06
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
			DERWENT;	
•		/	IBM_TDB USPAT;	2002/12/19 14:07
3	0		US-PGPUB;	2002/12/19 14:07
		(dielectric adj (layer or film))) same test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
		testss same (cuts4 of dics5 of separates)	DERWENT;	
			IBM TDB	
1	19	wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
1	19	(dielectric adj (layer or film))	US-PGPUB;	2002/12/13 14.0.
		(dielectic ad) (layer of lilm)	EPO; JPO;	
			DERWENT;	
			IBM TDB	i
4	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:38
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3	EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	963	438/15,110,113,114.ccls.	USPĀT	2002/12/19 14:38
6	1212	438/15,110,113,114.ccls.	USPAT;	2002/12/19 14:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	l o	438/15,110,113,114.ccls. and ((wafer adj	USPAT;	2002/12/19 14:40
		(bond\$3 or attach\$3) near4 (dielectric adj	US-PGPUB;	
		(layer or film))) same test\$3)	EPO; JPO;	
			DERWENT;	0,66
			IBM TDB	21
-	348	(438/15).CCLS.	USPĀT	2002/07/03 08:58
<u></u>	258	(438/113).CCLS.	USPAT	2002/07/03 08:58
-	94	(438/110).CCLS.	USPAT	2002/07/03 08:58
-	59	(438/114).CCLS.	USPAT	2002/07/03 08:58
-	681	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
-	401	438/15,110,113,114.ccls. and test\$3	USPAT	2001/08/07 15:09
_	272	(438/15,110,113,114.ccls. and test\$3) and	USPAT	2001/08/07 15:10
		(dice\$4 or cut\$5)		
-	901	438/15,110,113,114.ccls.	USPAT;	2002/02/04 09:53
			EPO; JPO;	
	4.60	420/15 110 112 1141- and back\$2	DERWENT	2002/02/04 00.54
-	460	438/15,110,113,114.ccls. and test\$3	USPAT; EPO; JPO;	2002/02/04 09:54
_	325	(438/15,110,113,114.ccls. and test\$3) and	DERWENT USPAT;	2002/02/05 08:26
_	323	(438/15,110,113,114.ccis. and test\$3) and (dic\$5 or cut\$5)	EPO; JPO;	2002/02/03 00:20
		(dicio or encis)	DERWENT	
_	5	(("6077757") or ("6335224") or ("6309943")	USPAT	2002/02/05 07:19
	,	or ("6309909") or ("6326697")).PN.	20171	2002,02,03 07.19
_	7	(("6077757") or ("6335224") or ("6309943")	USPAT	2002/02/05 09:49
_	·	or ("6309909") or ("6326697") or	332	2002,02,00 05.45
		("5858815") or ("5137836")).PN.		
_	326		USPAT;	2002/02/05 08:28
	320	(dic\$5 or cut\$5)	EPO; JPO;	1 202, 02, 03 00.20
		1	DERWENT	
_ 1	n	((438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:33
		(dic\$5 or cut\$5)) and (magnet\$7 adj	EPO; JPO;	
		align\$5)	DERWENT	
	170		USPAT;	, 2002/02/05 08:32
_	1.0	(dic\$5 or cut\$5)) and (align\$5)	EPO; JPO;	
-		(,	DERWENT	
-				,
-	2705	magnet\$7 adi align\$5		2002/02/05 08:56
-	2705	magnet\$7 adj align\$5	USPAT;	2002/02/05 08:56
-	2705	magnet\$7 adj align\$5	USPAT; EPO; JPO;	2002/02/05 08:56
_	2705		USPAT;	
-			USPAT; EPO; JPO; DERWENT	2002/02/05 08:56



-	0	wafer adj20 dielectric adj tape	USPAT;	2002/02/05 08:37
			EPO; JPO;	
			DERWENT	
-	0	wafer adj dielectric adj tape	USPAT;	2002/02/05 08:38
			EPO; JPO;	!
			DERWENT	
-	248	(magnet\$7 adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
	i		DERWENT	
-	0	(the great and manging) and zaring, and	USPAT;	2002/02/05 08:49
		(charged adj slot)	EPO; JPO;	
			DERWENT	
-	0	(magnet\$7 adj align\$5) and (charged adj	USPAT;	2002/02/05 08:49
		slot)	EPO; JPO;	
			DERWENT	
-	613	(magnet\$7 adj align\$5) and ring	USPAT;	2002/02/05 08:50
			EPO; JPO;	
1			DERWENT	
-	47	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:51
		semiconductor	EPO; JPO;	
			DERWENT	
_	3066	optically adj align\$5	USPAT;	2002/02/05 08:56
			EPO; JPO;	2002,02,03
			DERWENT	
-	612	(optically adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
		(if i = i = i = j = i	EPO; JPO;	2002/02/03 00.37
	ļ		DERWENT	
_	1 8	(("6077757") or ("6335224") or ("6309943")	USPAT	2002/02/05 09:49
		or ("6309909") or ("6326697") or	OSTAI	2002/02/03 09.49
		("5858815") or ("5137836") or	1	
		("4781969")).PN.		
_	10260	wood.inv.	USPAT;	2002/07/03 08:13
	10200	11000111111	US-PGPUB;	2002/07/03 08:13
			EPO; JPO;	
			DERWENT; IBM TDB	ĺ
_	539	wood.inv. and alan	USPAT;	2002/07/02 00 12
		wood:inv. and alan	1	2002/07/03 08:13
			US-PGPUB;	
			EPO; JPO;]
1			DERWENT;	1
_	232	(wood.inv. and alan) and (micron adj	IBM_TDB	0000 /07 /00 00 1
	232	technology)	USPAT;	2002/07/03 08:14
		cecimology,	US-PGPUB;	<u> </u>
			EPO; JPO;	
			DERWENT;	1
_	1	("6268650").PN.	IBM_TDB	2000/07/22 22 2
-	425	(438/15).CCLS.	USPAT	2002/07/03 08:30
- 1	331	(438/113).CCLS.	USPAT	2002/07/08 08:43
_	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
_	90	(438/114).CCLS.	USPAT	2002/07/08 08:57
1_	425	(438/114).CCLS.	USPAT	2002/07/08 08:57
_	331	(438/13).CCLS.	USPAT	2002/07/08 08:43
_	140	(438/113).CCLS.	USPAT	2002/07/08 08:57
_	90	(438/110).CCLS.	USPAT	2002/07/08 08:57
]_ [13		USPAT	2002/07/08 14:32
	13	(("6389689") or ("5977629") or ("5796170")	USPAT	2002/07/08 10:35
		or ("6326700") or ("6268650") or		
<u> </u>]	("5858815") or ("5817535") or ("5770032")	ì	1
	į	or ("4781969") or ("5073840") or	į	
		("5696033") or ("5834839") or		
_	ر ا	("6160714")).PN.		1
-	8	(("6309909") or ("5858815") or ("5137836")	USPAT	2002/07/09 09:56
1		or ("6077757") or ("6326697") or		
		("6165885") or ("5834320") or		
		("4781969")).PN.		
				